



SOT2013-2

HWFLGA16, thermal enhanced very-very thin fine-pitch land grid array package, 16 terminals, 0.4 mm pitch, 2 mm x 2 mm x 0.64 mm body

4 March 2021

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HWFLGA16
Package style descriptive code	LGA (land grid array package)
Mounting method type	S (surface mount)
Issue date	20-05-2020
Manufacturer package code	98ASA01440D

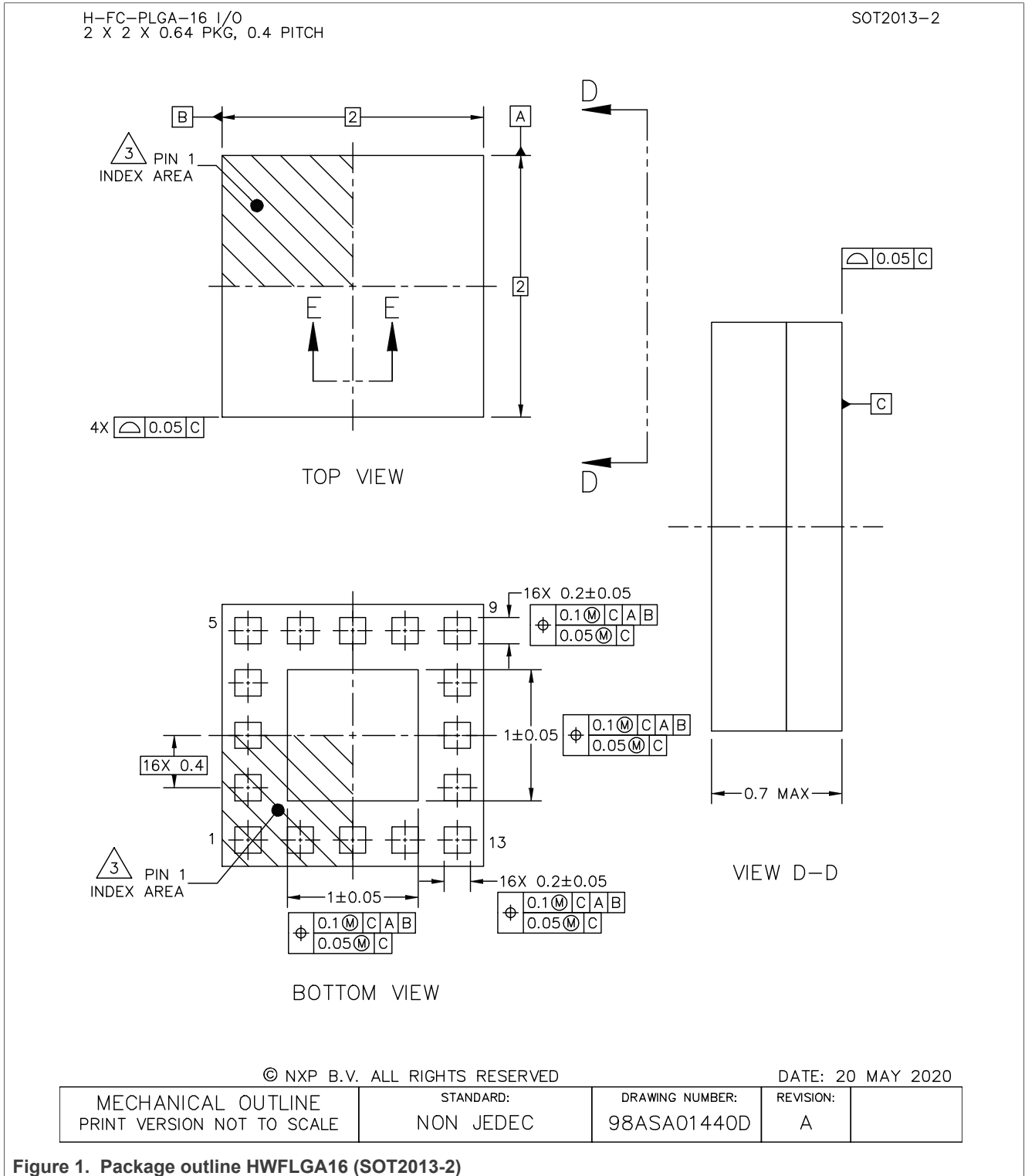
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.95	2	2.05	mm
package width	1.95	2	2.05	mm
package height	-	0.64	0.7	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	16	-	



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2 Package outline



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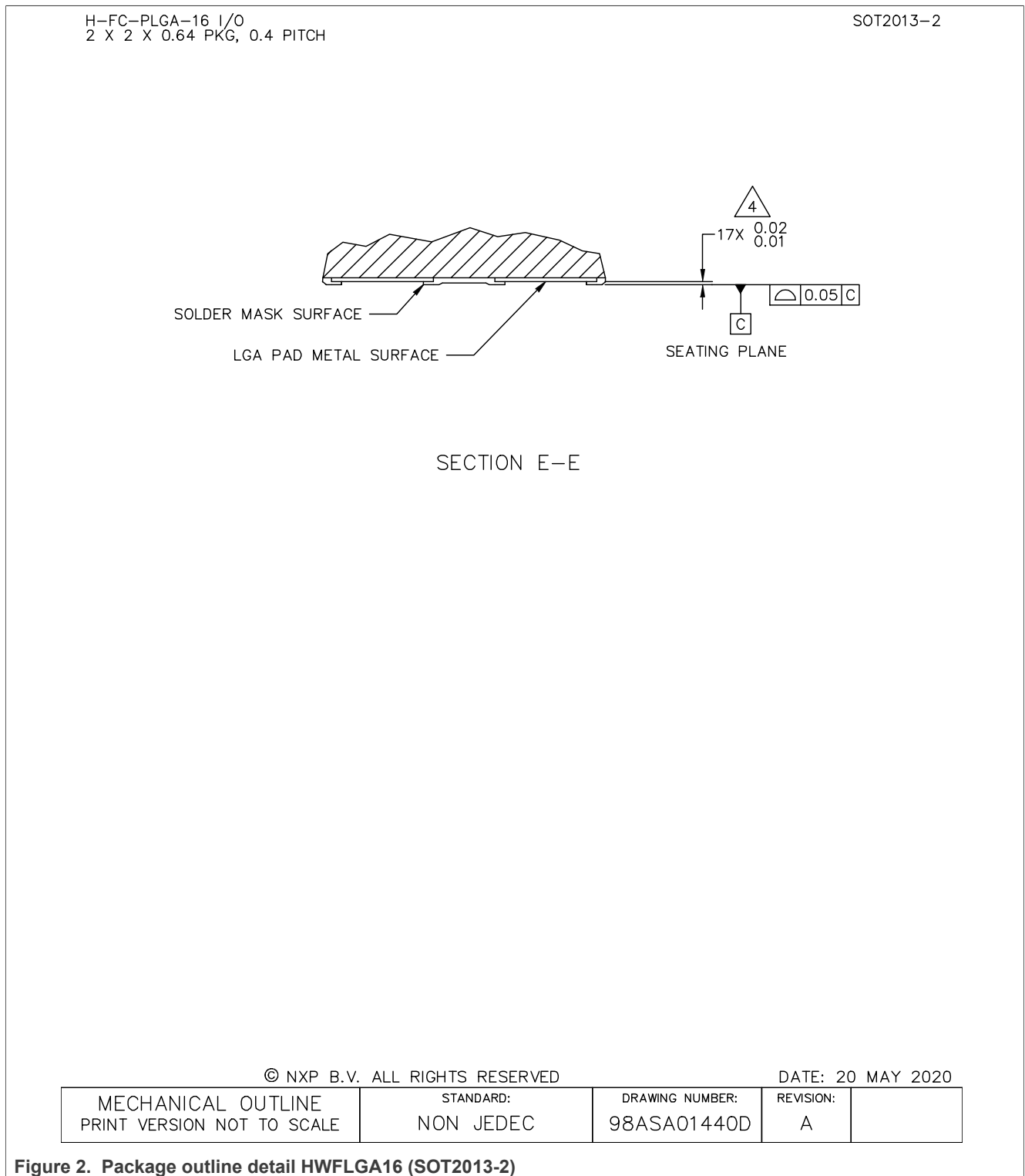
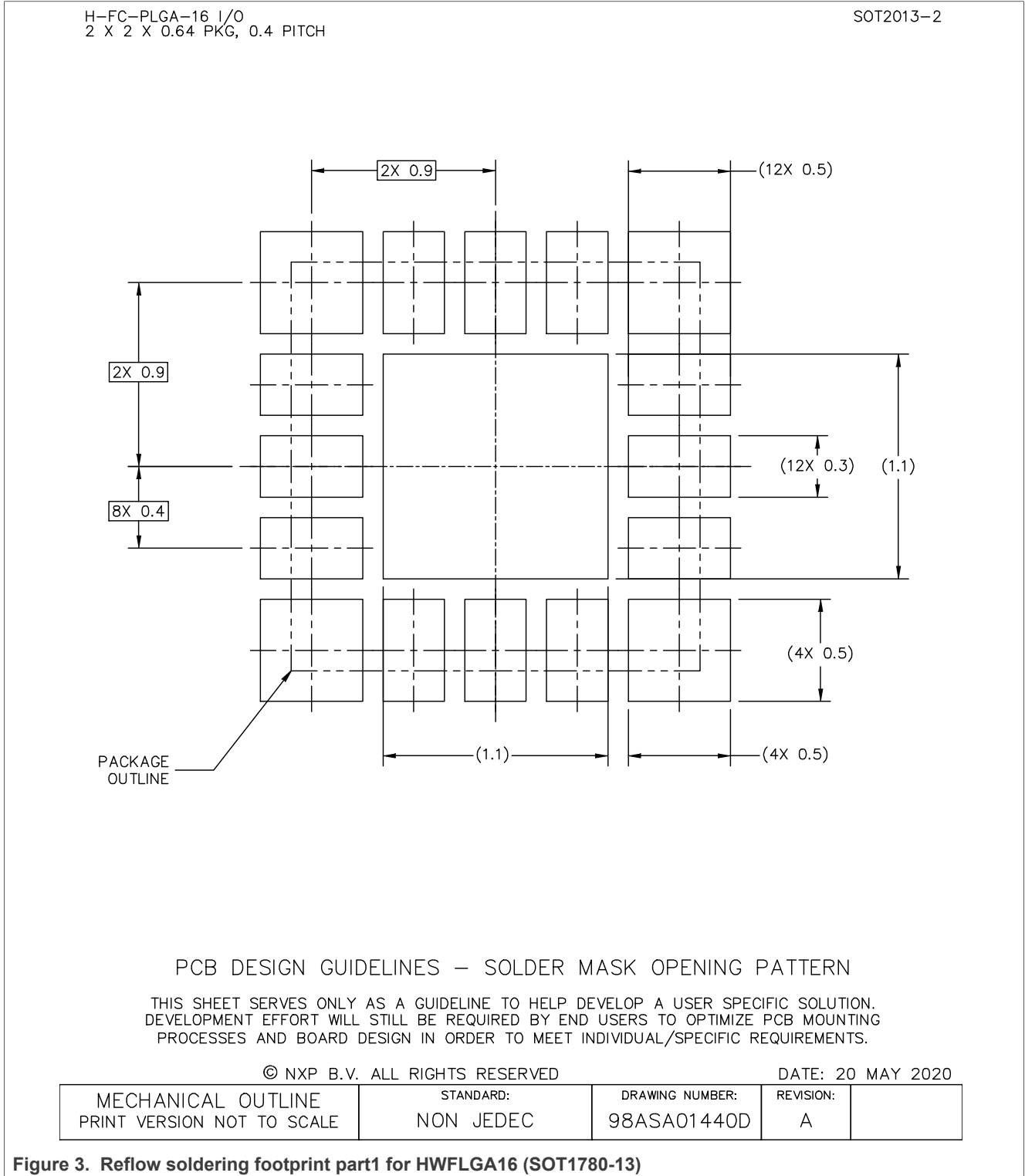


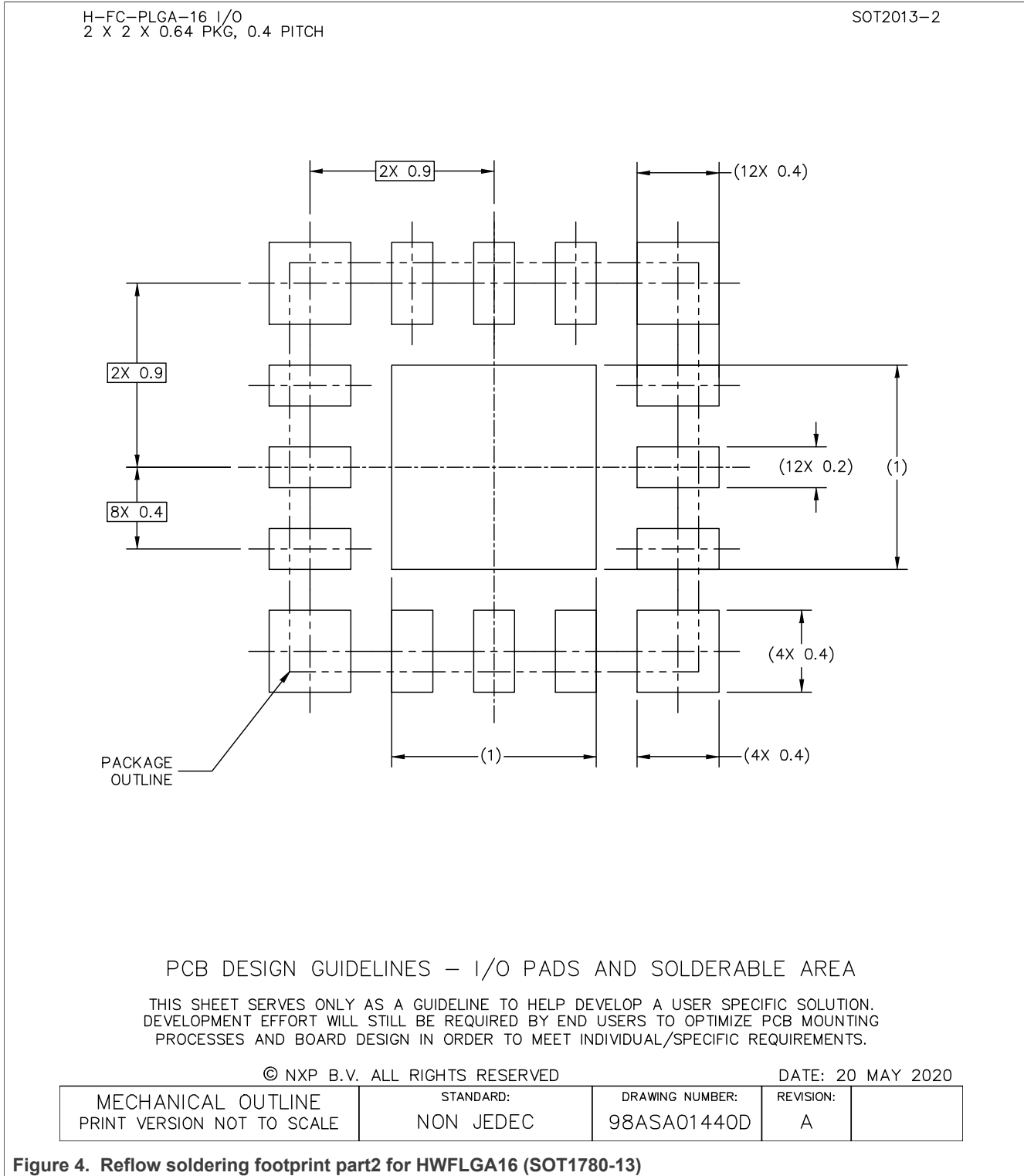
Figure 2. Package outline detail HWFLGA16 (SOT2013-2)

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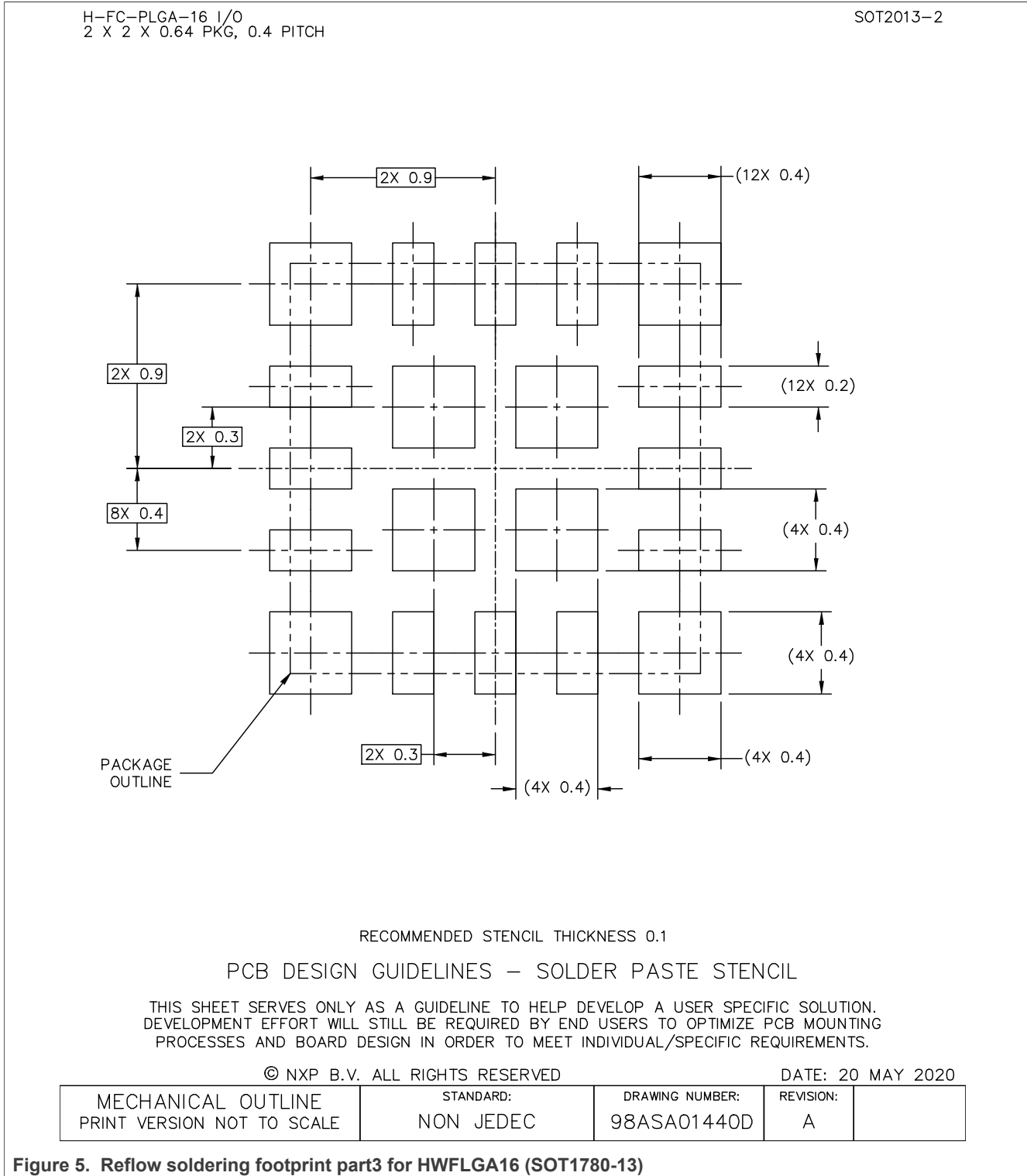
3 Soldering



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H-FC-PLGA-16 I/O
2 X 2 X 0.64 PKG, 0.4 PITCH

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NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.

4. DIMENSION APPLIES TO ALL LEADS.

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DATE: 20 MAY 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01440D	REVISION: A	
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Figure 6. Package outline note HWFLGA16 (SOT2013-2)

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4 Legal information

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